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Micro/Nano Photonics: Materials and Devices

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Introduction

Micro/nano-photonics is a rising interdisciplinary field focused on the study of the behavior of light on the micro/nano meter scale. It is considered a branch of optical engineering which deals with optics, or the interaction of light with particles or substances, at deep subwavelength length scales. Micro/nano-photonics can provide high bandwidth, high speed and ultra-small optoelectronic components. This technology has the potential to revolutionize telecommunications, computation, sensing, optical storage, optical display, optical manipulation, solar energy utilization, and lithography, etc.

With the importance of this technology in mind, the Micro/Nano-photonics, Materials and Devices Conference of OIT 2019 was organized. The conference accepted over 40 presentations from different countries/areas of the world, which are focused on the design, fabrication, and application of micro/nanostructures, and crossed many research disciplines including silicon photonics integration, active nanomaterials, plasmonics, biophotonics, nonlinear optics, nanostructure device, and fabrication technology. We also invited renowned scholars to present their cutting-edge breakthroughs. These experts and contributors added to an intellectually stimulating environment.

As the Conference Chairs, we would like to express our appreciation to the committee members for their support, to the presenters for devoting their precious time to writing intriguing articles, and to the reviewers for their helpful comments. We are also grateful to the staff of SPIE for their efforts in publishing these Proceedings.

Baojun Li
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